ABSTRACT

This document should be used in conjunction with the device data sheet and describes the updated package designator for the indicated devices.

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Trademarks

MicroStar BGA™ and MicroStar Junior™ are trademarks of Texas Instruments.
All other trademarks are the property of their respective owners.
1 Package Redesign Details

Explanation
The devices in the MicroStar BGA™ packaging were redesigned using a laminate nfBGA package. This nfBGA package offers datasheet-equivalent electrical performance. It is also footprint equivalent to the MicroStar BGA. For more details, please refer to this nfBGA Packaging Application Report.

When referencing the device data sheet, use the new package designator in place of the discontinued package designator throughout the document.

The orderable addendum at the end of the device data sheet will reflect the new package designator.

See the following page or the end of the device data sheet for the updated nfBGA package drawing.

<table>
<thead>
<tr>
<th>Table 1-1. Package Designator</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Old Package Designator</strong></td>
</tr>
<tr>
<td>GGU</td>
</tr>
<tr>
<td>ZGU</td>
</tr>
</tbody>
</table>

Reason for Discontinuance
Due to an equipment End-Of-Life notice from our substrate supplier, we are phasing out certain MicroStar BGA and MicroStar Junior™ BGA packaging devices and offering a Last Time Buy.

These devices have now been converted to an nfBGA package.

Devices Affected
The following table describes the devices affected, the old and new package designators, and references to the device data sheet.

<table>
<thead>
<tr>
<th>Table 1-2. Devices and Nomenclature</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Device</strong></td>
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<tr>
<td>TMS320VC5416</td>
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<td>TMS320VC5416</td>
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<tr>
<td>TMS320VC5416</td>
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<tr>
<td>TMS320VC5416</td>
</tr>
</tbody>
</table>
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

2. This drawing is subject to change without notice.

NanoFree is a trademark of Texas Instruments.
3. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. Refer to Texas Instruments Literature number SNVA009 (www.ti.com/lit/snva009).
4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
NOTES: (continued)

3. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For information, see Texas Instruments literature number SPRAA99 (www.ti.com/lit/spraa99).
4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.
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